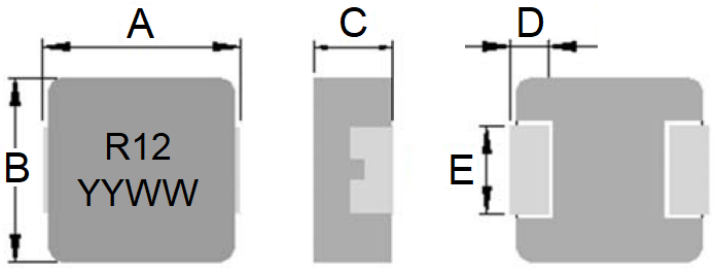
## 1. Part No. Expression

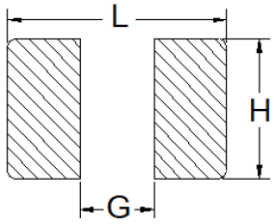
**P I C 0 6 0 4 H R 1 2 Y F**

(a) (b) (c) (d) (e) (f)

| | | | |
|---|---|---|---|
| (a) | Series Code | (d) | Inductance Code |
| (b) | Dimension Code | (e) | Tolerance Code |
| (c) | Material Code | (f) | Packaging Code |

## 2. Configuration & Dimensions (Unit: mm)




Recommended PCB Layout

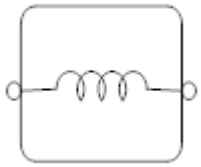
Note: 1. The above PCB layout reference only.

2. Recommend solder paste thickness at 0.15 mm and above.

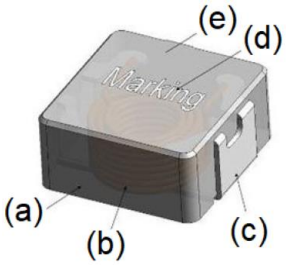
3. Marking: Top= Inductance Code, Bottom=YYWW (Year/World week), Black

| A | B | C | D | E | L | G | H |
|---|---|---|---|---|---|---|---|
| 7.3±0.3 | 6.6±0.3 | 3.8±0.2 | 1.8±0.3 | 3.0±0.3 | 8.4 Ref | 2.5 Ref | 3.5 Ref |

## 3. Schematic



## 4. Material List




| NO | Items |
|---|---|
| (a) | Core |
| (b) | Wire |
| (c) | Clip |
| (d) | Ink |
| (e) | Paint |

## 5. General Specifications

(a) Operating Temp.: - 40°C to + 125°C (including self-temperature rise)

(b) Storage Temp.: - 40°C to + 125°C (on board)

(c) All test data referenced to 25°C ambient.

(d) Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C.

(e) Saturation Current (Isat) will cause inductance L0 to drop approximately 30%.

(f) Rated DC Current: The lower value of Irms and Isat.

(g) Part Temperature (Ambient + Temp. Rise): Should not exceed 125°C under worst case operating conditions.

(h) Maximum Operating Voltage: 50V

(i) Storage Condition (Component in its packaging)

i) Temperature: Less than 40°C

ii) Humidity: Less than 60% RH

NOTE: Specifications subject to change without notice. Please check our website for latest information.

## 6. Electrical Characteristics

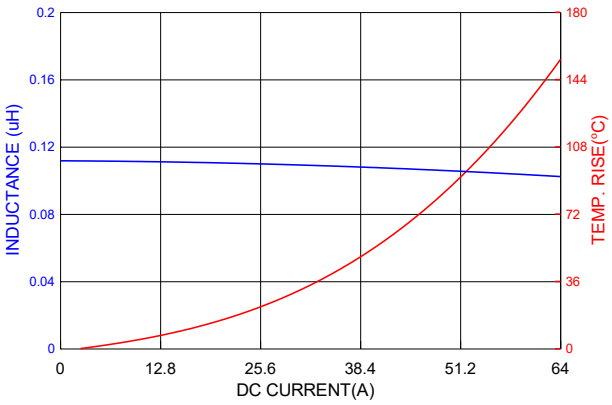
| Part Number | Inductance (μH) @0A | Test Frequency | Irms (A) Typ | Isat (A) Typ | DCR (mΩ) | |
|---|---|---|---|---|---|---|
| | | | | | Typ | Max |
| PIC0604HR12YF | 0.12 | 1.0V/100KHz | 32.0 | 64.0 | 0.7 | 1.0 |
| PIC0604HR15YF | 0.15 | 1.0V/100KHz | 30.0 | 55.0 | 0.9 | 1.2 |
| PIC0604HR36MF | 0.36 | 1.0V/100KHz | 25.0 | 31.0 | 2.7 | 3.1 |
| PIC0604HR47MF | 0.47 | 1.0V/100KHz | 23.0 | 28.0 | 3.0 | 3.4 |
| PIC0604HR56MF | 0.56 | 1.0V/100KHz | 20.0 | 26.0 | 3.8 | 4.3 |
| PIC0604HR68MF | 0.68 | 1.0V/100KHz | 16.0 | 24.0 | 4.1 | 4.5 |
| PIC0604H1R0MF | 1.00 | 1.0V/100KHz | 14.0 | 22.0 | 6.8 | 8.0 |
| PIC0604H1R5MF | 1.50 | 1.0V/100KHz | 12.0 | 20.0 | 10.0 | 12.0 |
| PIC0604H2R2MF | 2.20 | 1.0V/100KHz | 9.0 | 14.0 | 11.5 | 14.0 |
| PIC0604H3R3MF | 3.30 | 1.0V/100KHz | 8.0 | 12.0 | 24.0 | 27.0 |
| PIC0604H4R7MF | 4.70 | 1.0V/100KHz | 6.0 | 11.0 | 28.0 | 32.5 |
| PIC0604H5R6MF | 5.60 | 1.0V/100KHz | 5.0 | 9.0 | 33.0 | 38.0 |
| PIC0604H6R8MF | 6.80 | 1.0V/100KHz | 4.5 | 8.5 | 44.0 | 50.0 |
| PIC0604H8R2MF | 8.20 | 1.0V/100KHz | 4.5 | 8.0 | 55.0 | 64.0 |
| PIC0604H100MF | 10.0 | 1.0V/100KHz | 4.0 | 7.0 | 64.0 | 72.0 |
| PIC0604H150MF | 15.0 | 1.0V/100KHz | 3.0 | 3.5 | 80.0 | 90.0 |
| PIC0604H330MF | 33.0 | 1.0V/100KHz | 1.8 | 3.2 | 180 | 210 |

Tolerance Code: M =±20%, Y =±30%

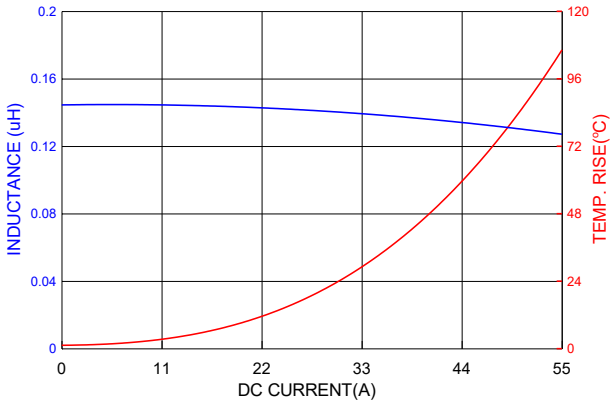
NOTE: Specifications subject to change without notice. Please check our website for latest information.

## 7. Characteristics Curve

PIC0604HR12YF




PIC0604HR15YF

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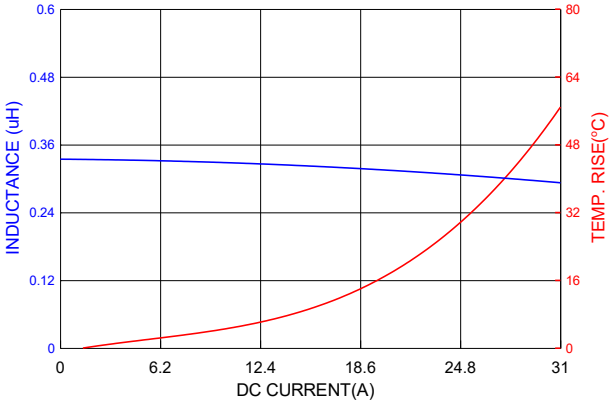


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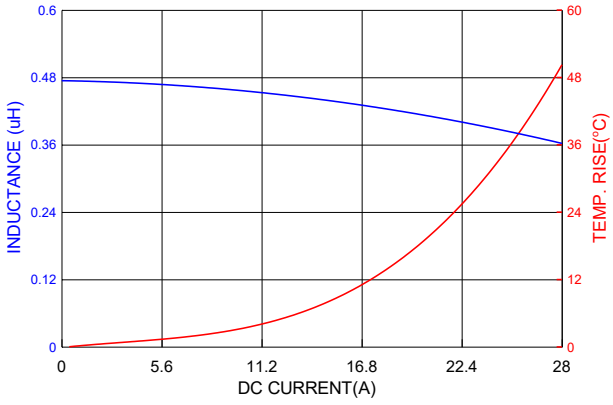
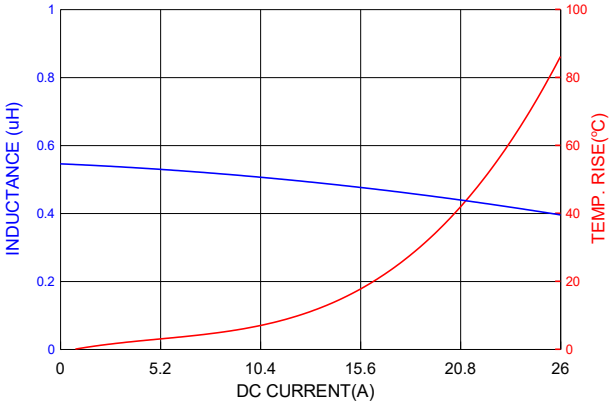
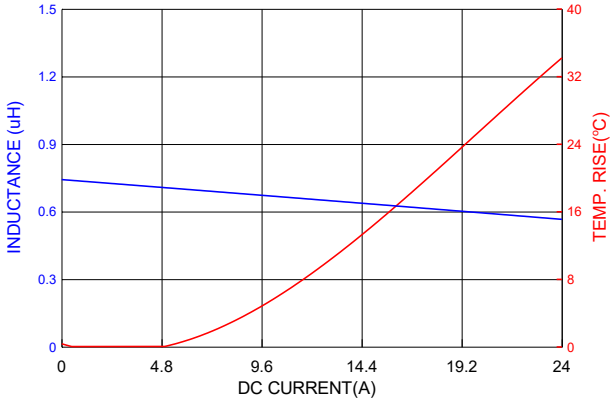



PIC0604HR56MF

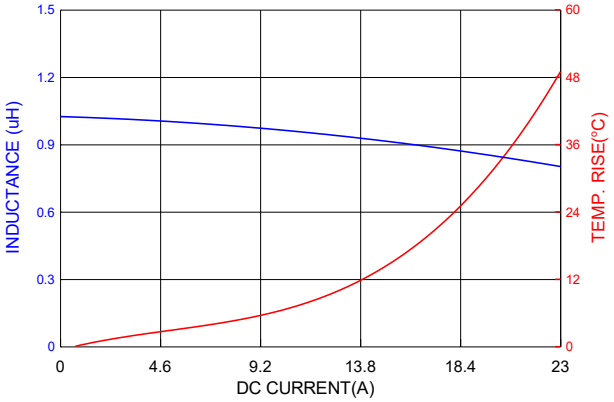



PIC0604HR68MF

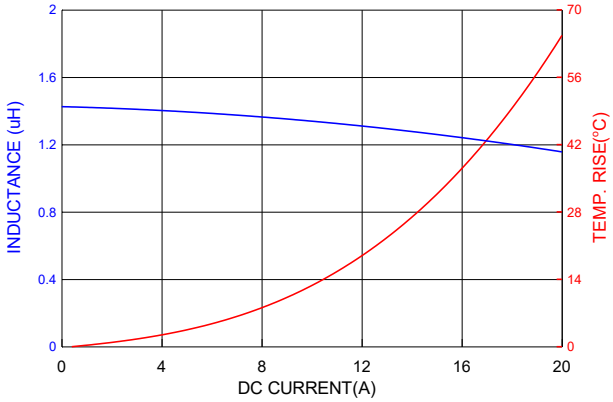



NOTE: Specifications subject to change without notice. Please check our website for latest information.

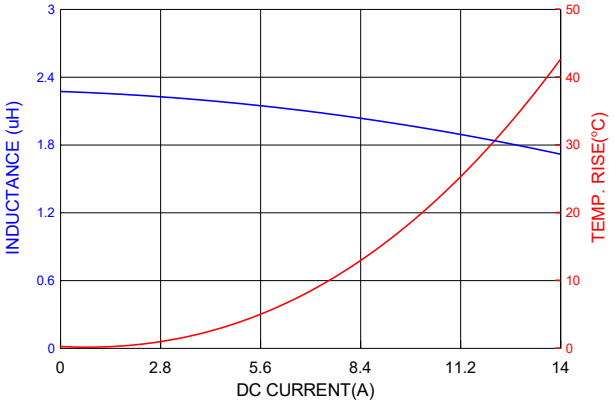
PIC0604H1R0MF



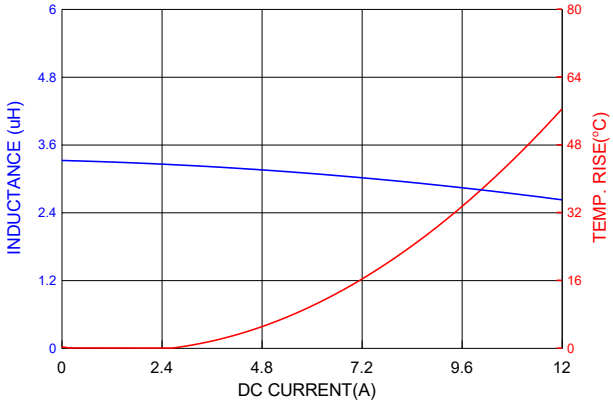

PIC0604H1R5MF



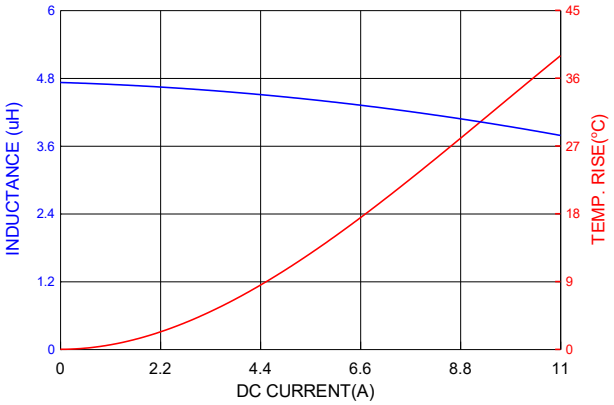

PIC0604H2R2MF



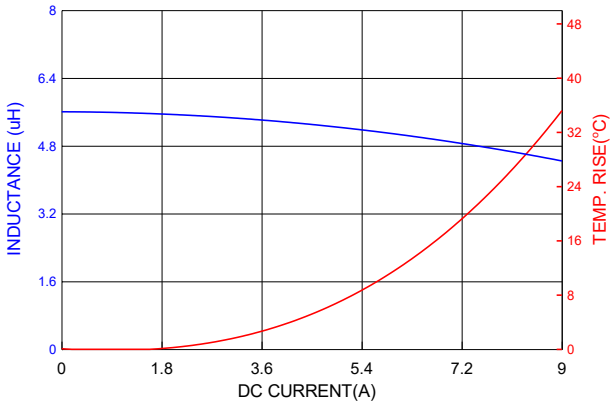

PIC0604H3R3MF




PIC0604H4R7MF

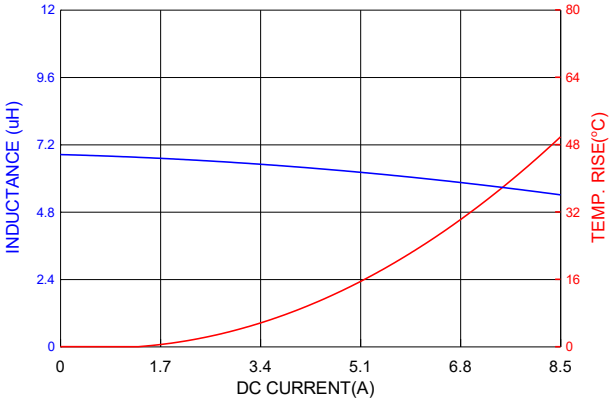



PIC0604H5R6MF

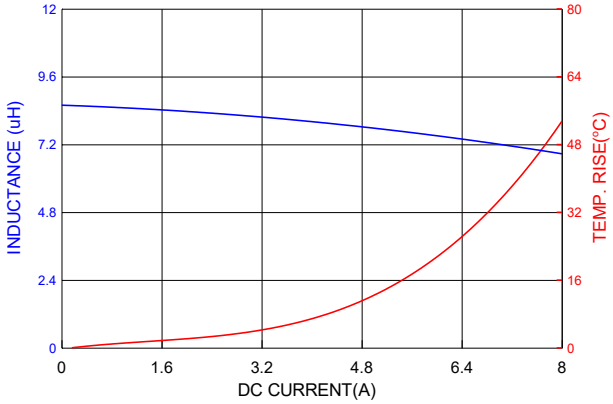



NOTE: Specifications subject to change without notice. Please check our website for latest information.

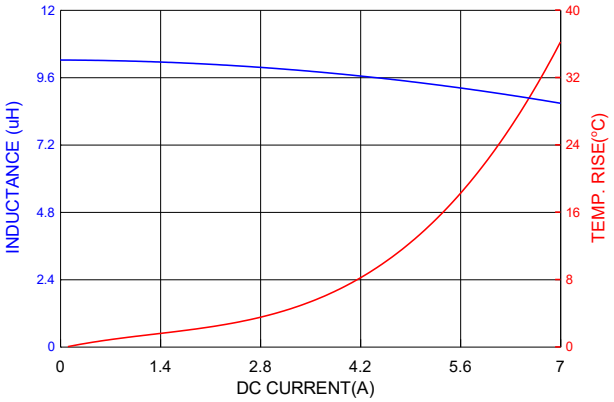
PIC0604H6R8MF



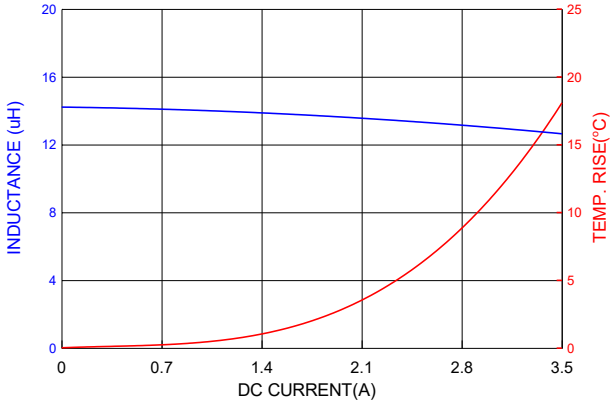

PIC0604H8R2MF



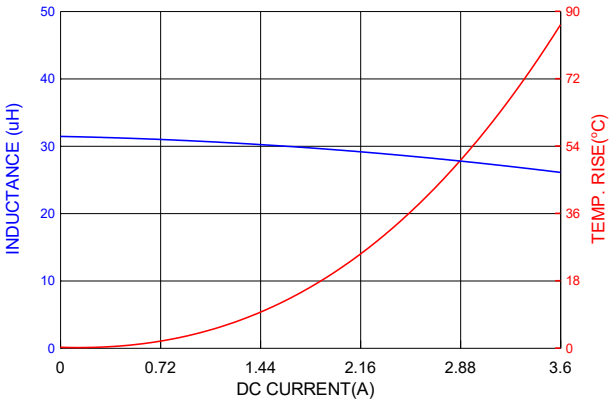

PIC0604H100MF




PIC0604H150MF




PIC0604H330MF




NOTE: Specifications subject to change without notice. Please check our website for latest information.

## 8. Soldering Specification

Mildly activated rosin fluxes are preferred. Our terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### 8-1. IR Soldering Reflow

Recommended temperature profiles for lead free re-flow soldering in Figure 1, Table 1.1 & 1.2 (J-STD-020E).

### 8-2. Iron Reflow

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended (Figure 2).

Note:

(a) Preheat circuit and products to 150°C.

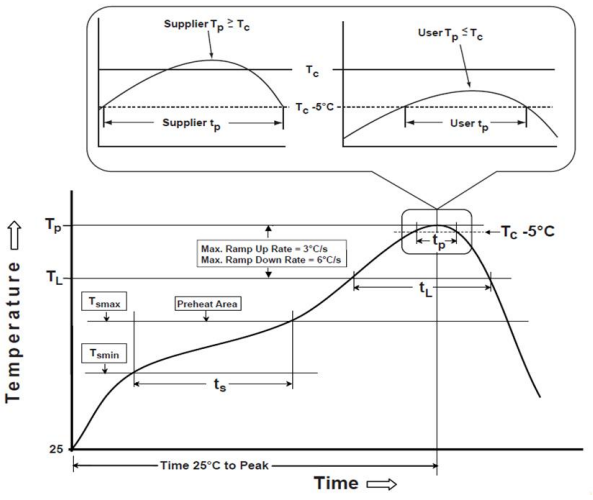
(b) 355°C tip temperature (Max.)

(c) Never contact the ceramic with the iron tip

(d) 1.0mm tip diameter (Max.)

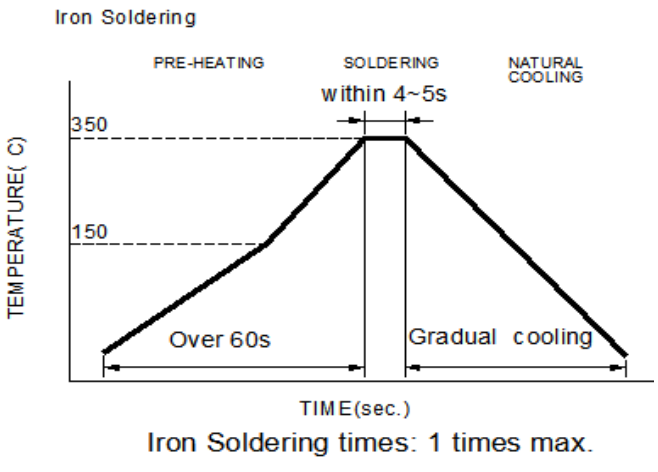
(e) Use a 20 watt soldering iron with tip diameter of 1.0mm

(f) Limit soldering time to 4~5 sec.




Reflow times: 3 times Max

Figure 1: IR Soldering Reflow




Soldering iron method: 350±5°C Max

Figure 2: Iron soldering temperature profiles

NOTE: Specifications subject to change without notice. Please check our website for latest information.

**Table (1.1) Reflow Profiles**

| Profile Type: | Pb-Free Assembly |
|---|---|
| Preheat<br>-Temperature Min ($T_{smin}$)<br>-Temperature Max ($T_{smax}$)<br>-Time ($t_s$) from ($T_{smin}$ to $T_{smax}$) | <br>150°C<br>200°C<br>60-120seconds |
| Ramp-up rate ($T_L$to $T_p$) | 3°C /second max. |
| Liquids temperature ($T_L$)<br>Time ($t_L$) maintained above $T_L$ | 217°C<br>60-150 seconds |
| Classification temperature ($T_c$) | See Table (1.2) |
| Time ($t_p$) at Tc- 5°C (Tp should be equal to or less than Tc.) | *< 30 seconds |
| Ramp-down rate ($T_p$ to $T_L$) | 6°C /second max. |
| Time 25°C to peak temperature | 8 minutes max. |

**Tp**: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc.**

*Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

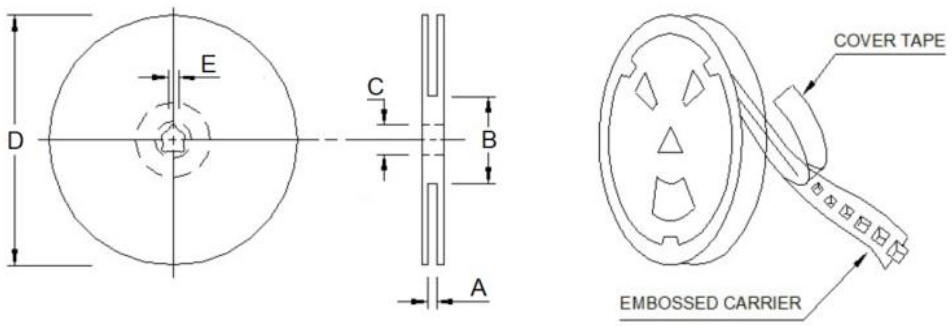
**Table (1.2) Package Thickness/Volume and Classification Temperature ($T_c$)**

| | Package Thickness | Volume $mm^3$ <350 | Volume $mm^3$ 350-2000 | Volume $mm^3$ >2000 |
|---|---|---|---|---|
| PB-Free Assembly | <1.6mm | 260°C | 260°C | 260°C |
| | 1.6-2.5mm | 260°C | 250°C | 245°C |
| | ≥2.5mm | 250°C | 245°C | 245°C |

Reflow is referred to standard IPC/JEDEC J-STD-020E.

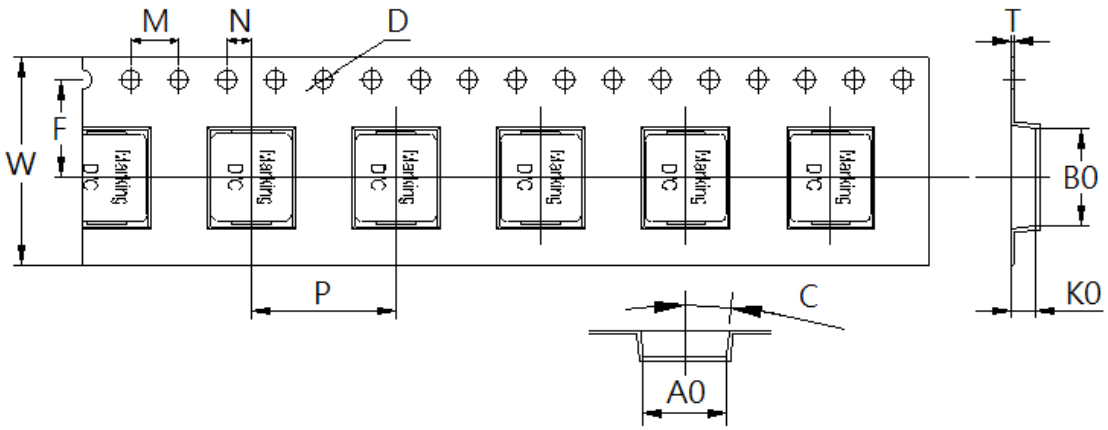
## 9. Packaging Information

### 9-1. Reel Dimension (Unit: mm)




| Type | A | B | C | D | E |
|---|---|---|---|---|---|
| 13”x16mm | 16.4+2.0/-0.0 | 100.0±2.0 | 13.0+0.5/-0.2 | 330.0 | 2.0±0.5 |

### 9-2. Tape Dimension (Unit: mm)



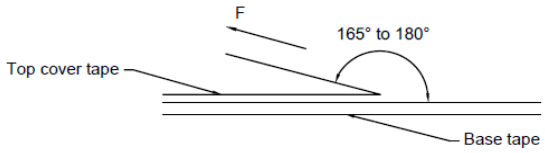

| B0 | A0 | K0 | P | W | F |
|---|---|---|---|---|---|
| 7.70±0.10 | 7.00±0.10 | 4.30±0.10 | 12.00±0.10 | 16.00±0.30 | 7.50±0.10 |
| T | M | N | D | C | - |
| 0.35±0.05 | 4.00 | 2.00 | 1.50±0.10 | 3° | - |

NOTE: Specifications subject to change without notice. Please check our website for latest information.

### 9-3. Packaging Quantity (Unit: Pcs)

| | |
|---|---|
| Chip/ Reel | 1,000 |
| Inner box | 2,000 |
| Carton | 8,000 |

### 9-4. Tearing Off Force




The force for tearing off cover tape is according to the follow table, in the arrow direction under the following conditions.
(Referenced ANSI/EIA-481-D-2008 of 4.11 standard)

| Room Temp. (°C) | Room Humidity (%) | Room atm (hPa) | Tearing Speed (mm/min) |
|---|---|---|---|
| 5~35 | 45~85 | 860~1060 | 300±10 |

| Tape Size | 8 mm | 12 to 56 mm | 72 mm or Wider |
|---|---|---|---|
| Tearing Off Force (grams) | 10~100 | 10~130 | 10~150 |

## Application Notice

1. Storage Conditions

To maintain the solderability of terminal electrodes:

(a) Recommended products should be used within 12 months from the time of delivery.

(b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation

(a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.

(b) Vacuum pick up is strongly recommended for individual components.

(c) Bulk handling should ensure that abrasion and mechanical shock are minimized.